



# Electronic Filing System (EFS) Data **Electronic Patent Application Submission USPTO** Use Only

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Application ID:

10774893

Title of Invention:

LEADFRAME FOR A

SEMICONDUCTOR PACKAGE

First Named Inventor:

**HYUNG LEE** 

Domestic/Foreign Application: Domestic Application

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Information Disclosure

Statement

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### **TRANSMITTAL**

Électronic Version v1.1 Stylesheet Version v1.1.0

Title of Invention

LEADFRAME FOR A SEMICONDUCTOR PACKAGE

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10/774893

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2004-02-09

First Named Applicant:

HYUNG JU LEE

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8761

Attorney Docket Number: AMKOR006C

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Submitted by:	Elec. Sign.	Sign. Capacity	
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney	

Documents being submitted

**Files** 

us-ids

ids5-usidst.xml

us-ids.dtd

us-ids.xsl

Comments



## **ELECTRONIC INFORMATION DISCLOSURE STATEMENT**

Electronic Version v18 Stylesheet Version v18.0

> Title of Invention

LEADFRAME FOR A SEMICONDUCTOR PACKAGE

Application Number:

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Confirmation Number:

8761

First Named Applicant:

**HYUNG LEE** 

Attorney Docket Number: AMKOR006C

Art Unit:

2811

Search string:

(6143981 or 6169329 or 6177718 or 6181002 or 6184573 or 6184465 or 6194777 or 6197615 or 6198171 or 6201186 or 6201292 or 6204554 or 6208023 or 6208020 or 6208021 or 6211462 or 6218731 or 6222258 or 6222259 or 6225146 or 6229200 or 6229205 or 6239367 or 6239384 or 6242281 or 6256200 or 6258629 or 6281566 or 6281568 or 6282095 or 6285075 or 6291271 or 6291273 or 6294100 or 6294830 or 6295977 or 6297548 or 6303984 or 6303997 or 6307272 or 6309909 or 6316822 or 6316838 or 6323550 or 6326243 or 6326244 or 6326678 or 6335564

or 6337510 or 6339255 ).pn.

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Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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## Signature

Examiner Name	Date